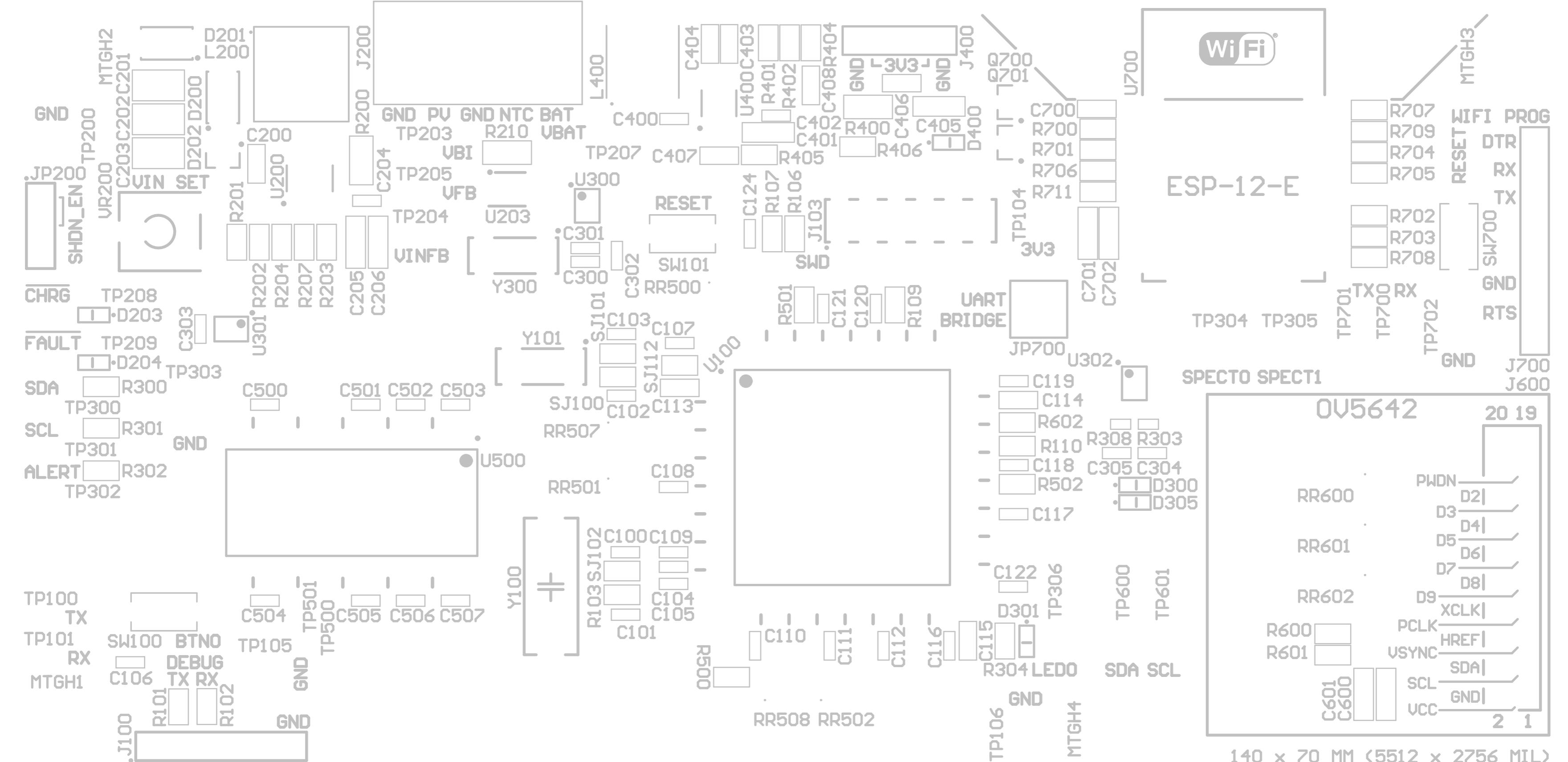


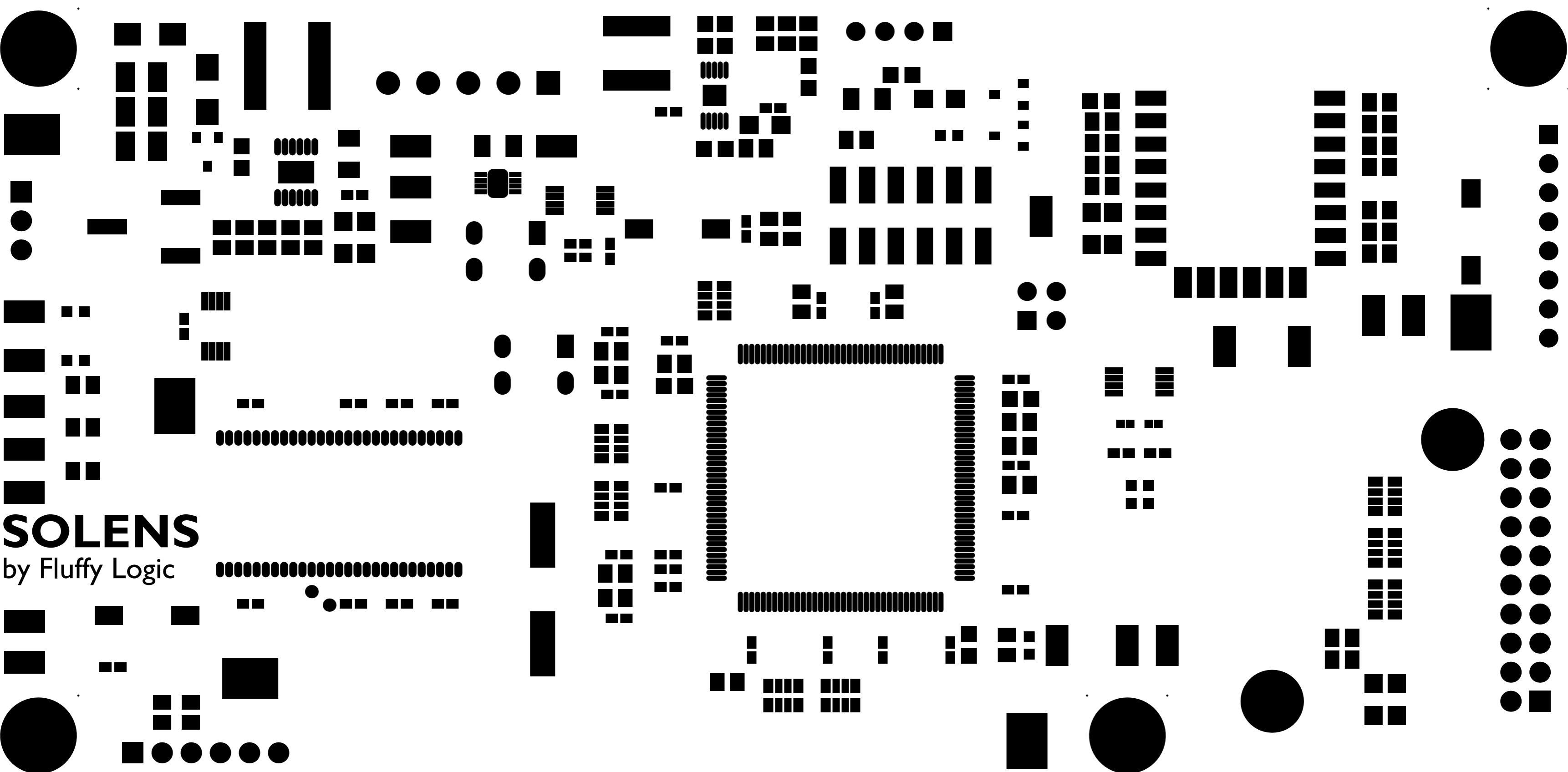
# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		Top Layer	Copper	1.37mil	
5		Dielectric 1	2x2116	9.80mil	4.2
6		Signal Layer 2	Copper	1.37mil	
7		Dielectric 4		40.00mil	4.2
8		Signal Layer 1	Copper	1.37mil	
9		Dielectric 3	2x2116	9.80mil	4.2
10		Bottom Layer	Copper	1.37mil	
11		Bottom Solder	Solder Resist	0.40mil	3.5
12		Bottom Overlay			
13		Bottom Paste			
Height : 65.88mil					



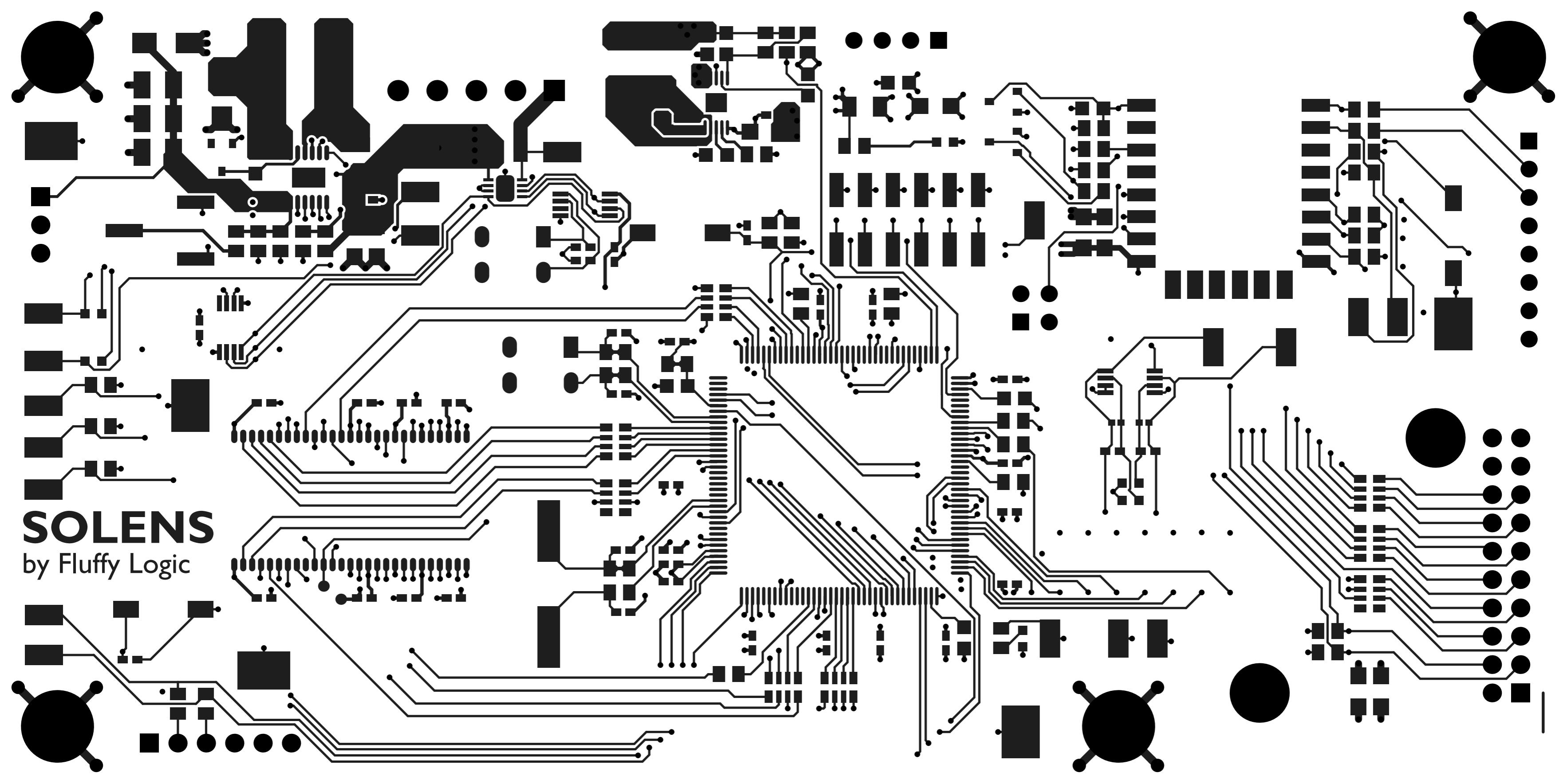
# SOLENS

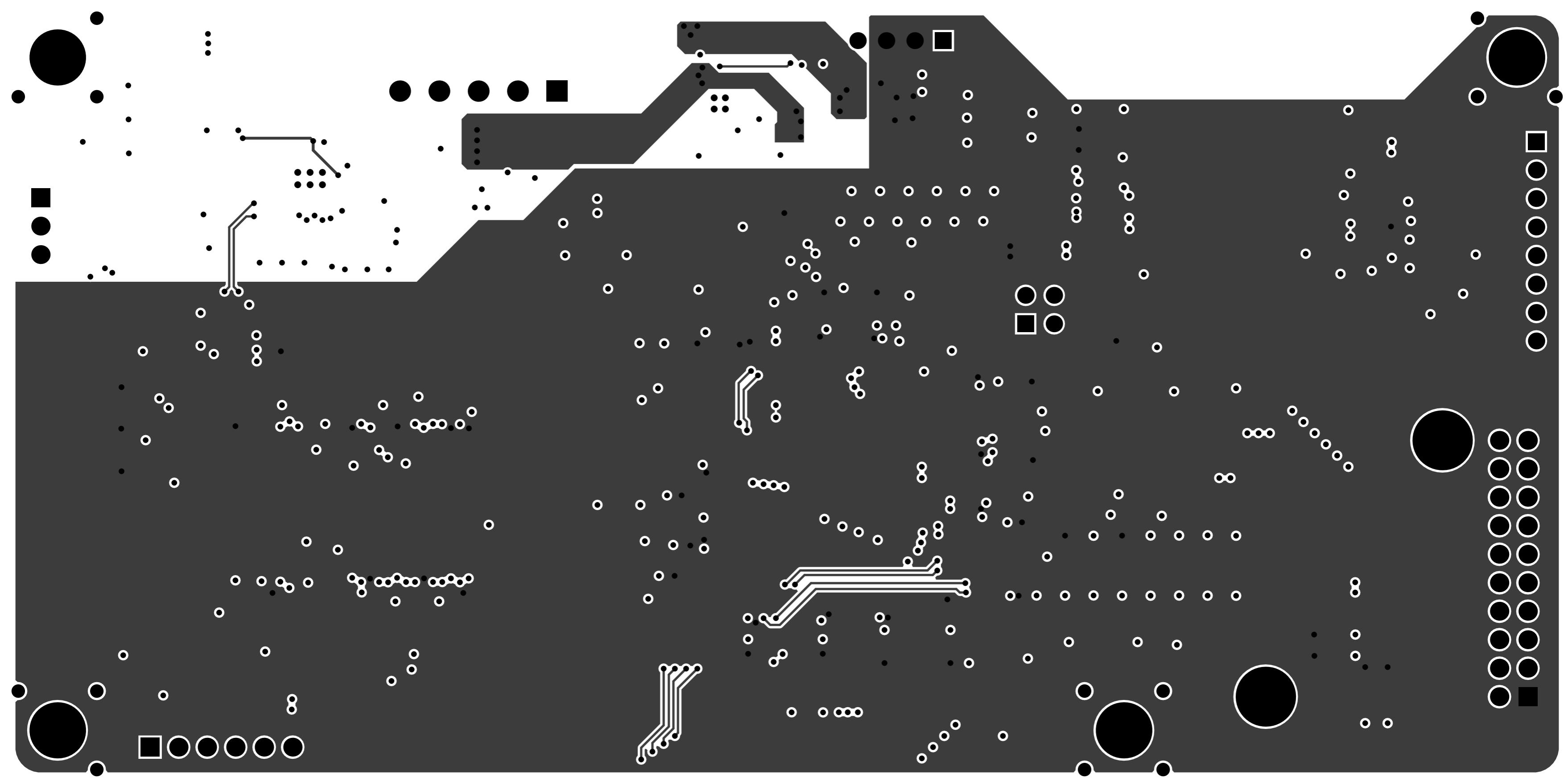
by Fluffy Logic

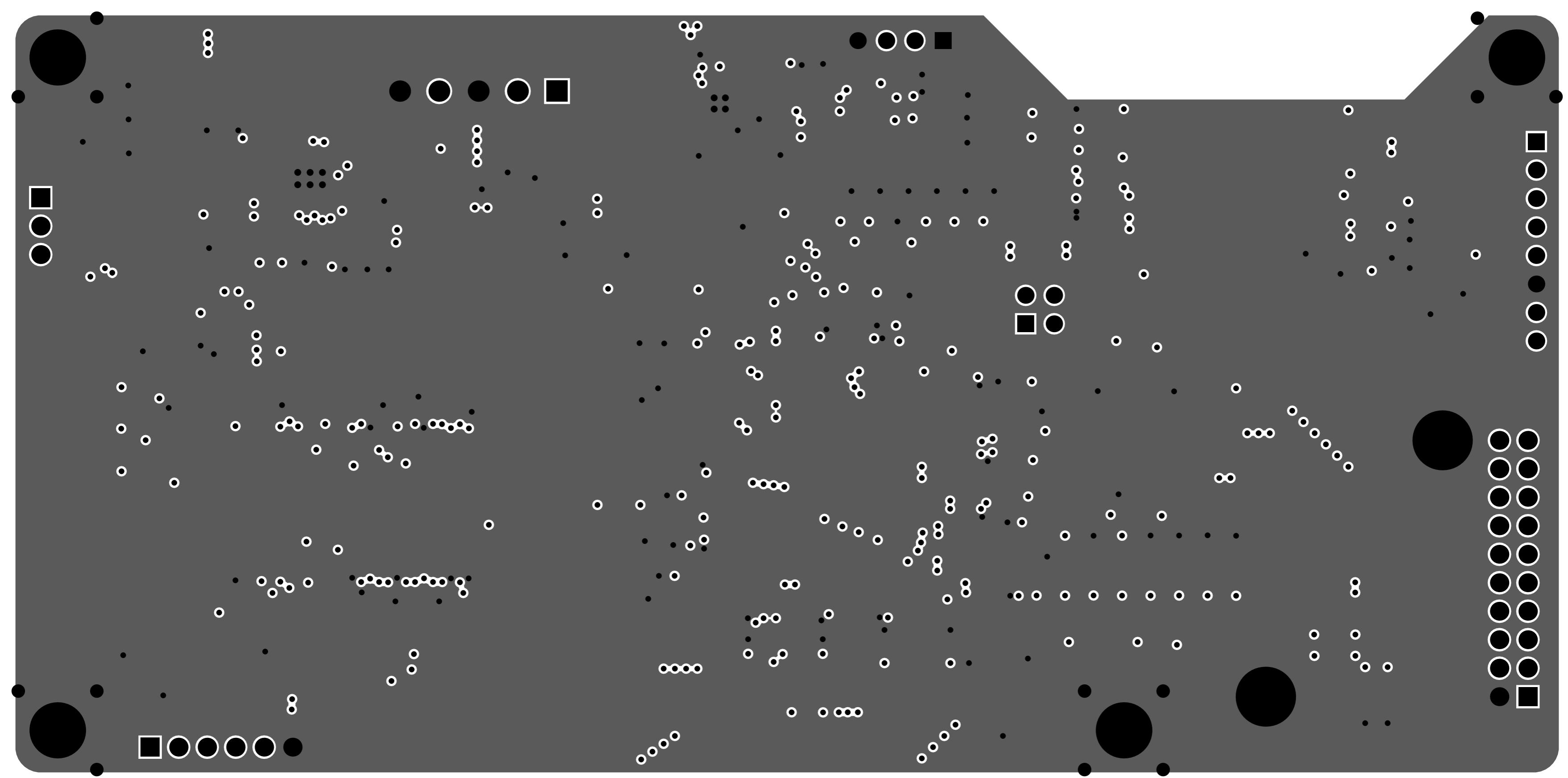


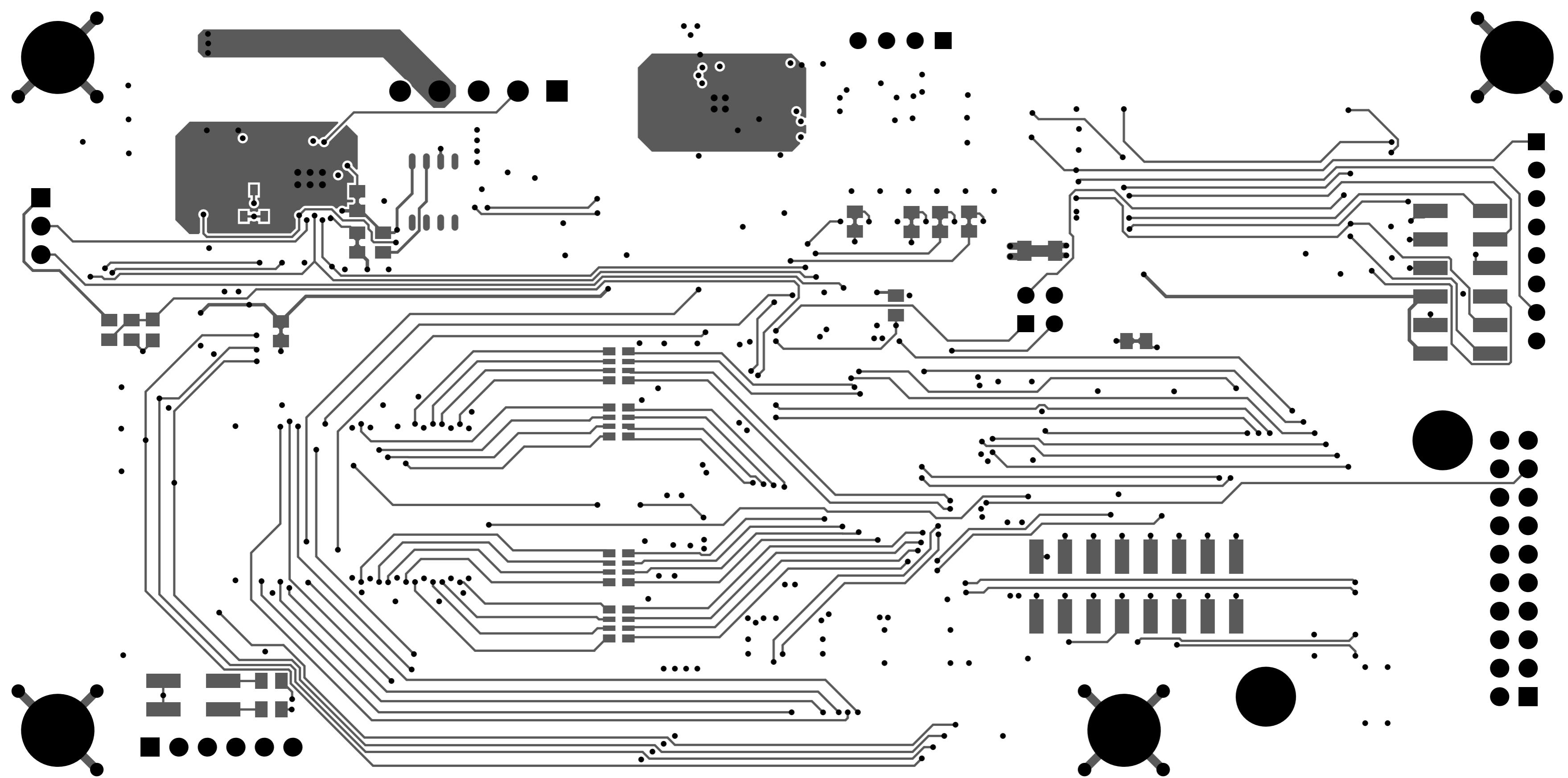
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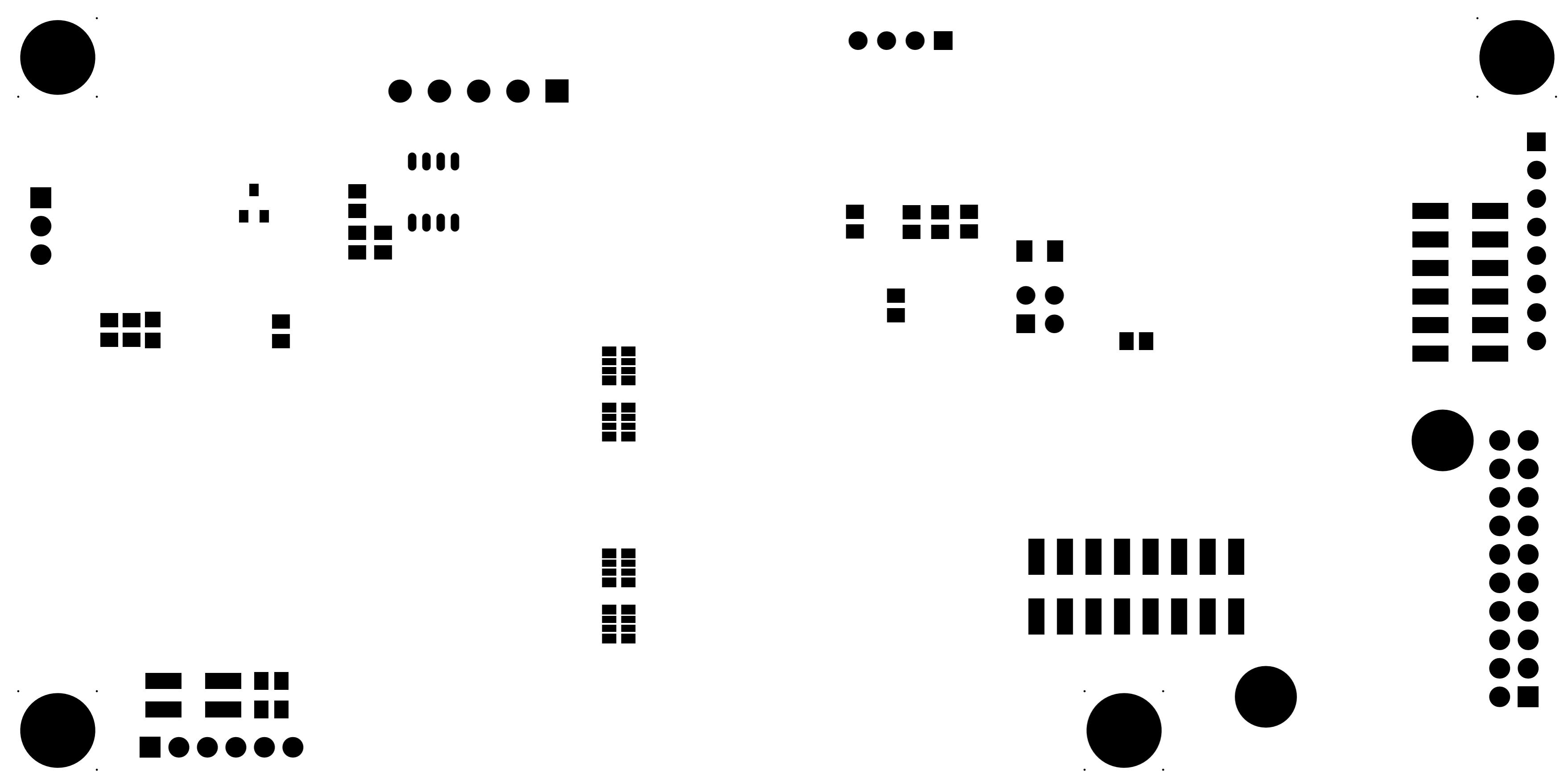
by Fluffy Logic











Ben Hepferlein  
Jeffrey Lim  
Taylor Nguyen  
Jeremy Rapp  
Akira Youngblood

2008  
2008  
2008

S1300 PERIPH  
PMR EN S1200  
S1200 EMPCO  
S1200 FLOAT  
S1200 SET  
S1200 TIMER  
RF3 RFB  
LJ 0300

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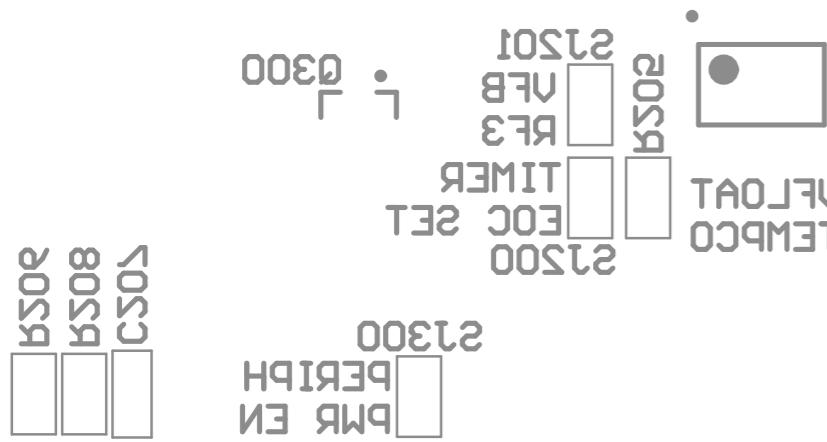
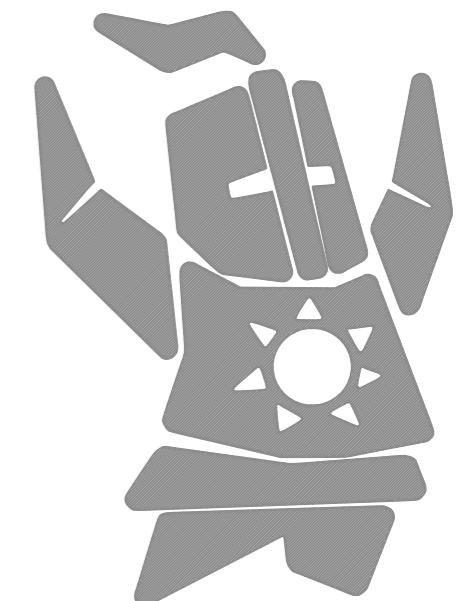
MM 041  
MM 031  
MM 021  
MM 011

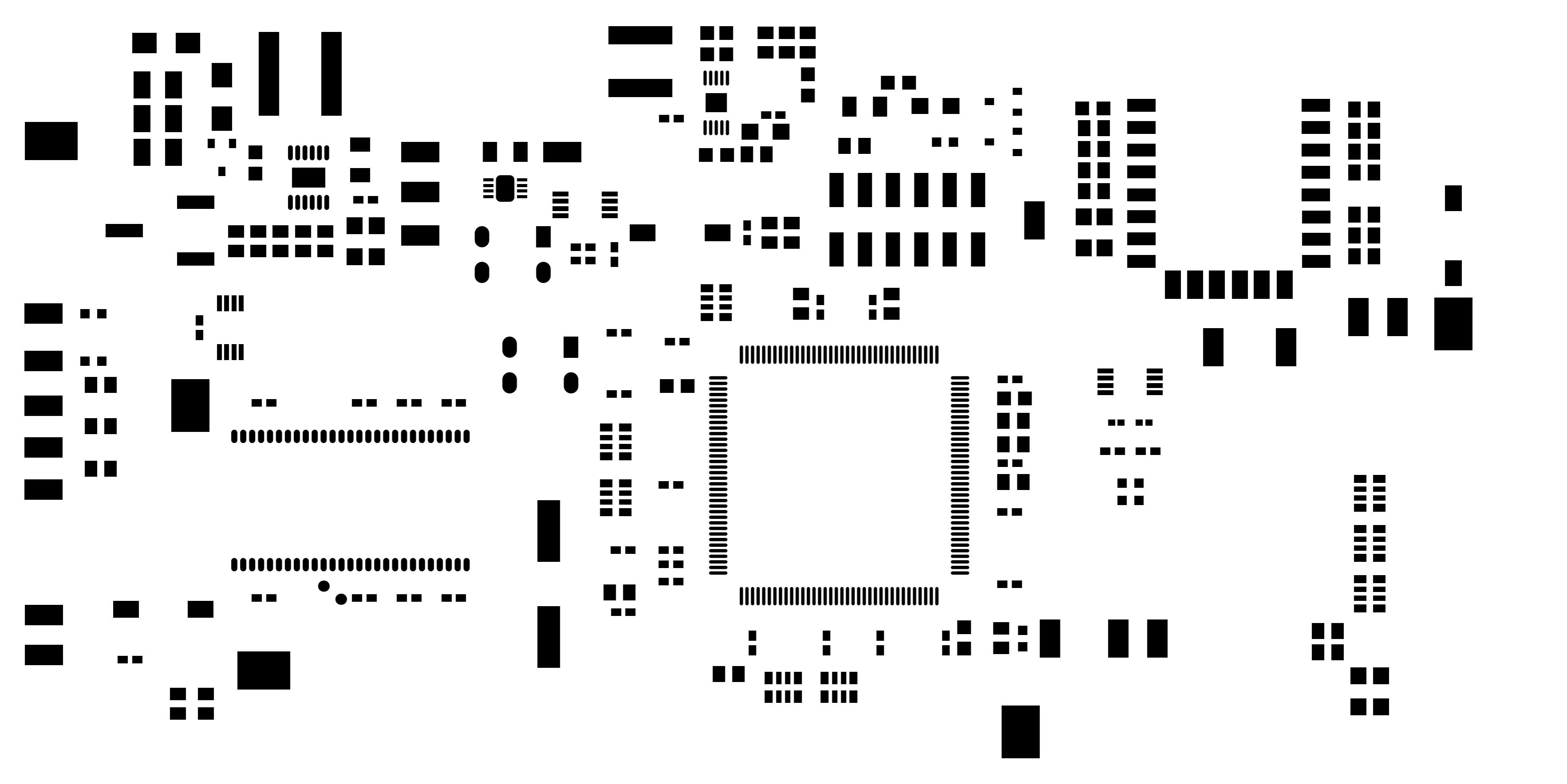
רְזָבֶחֶת  
סַדִּיר  
מְשֻׁתָּה  
גַּתְּוָה  
סַלְוֵה

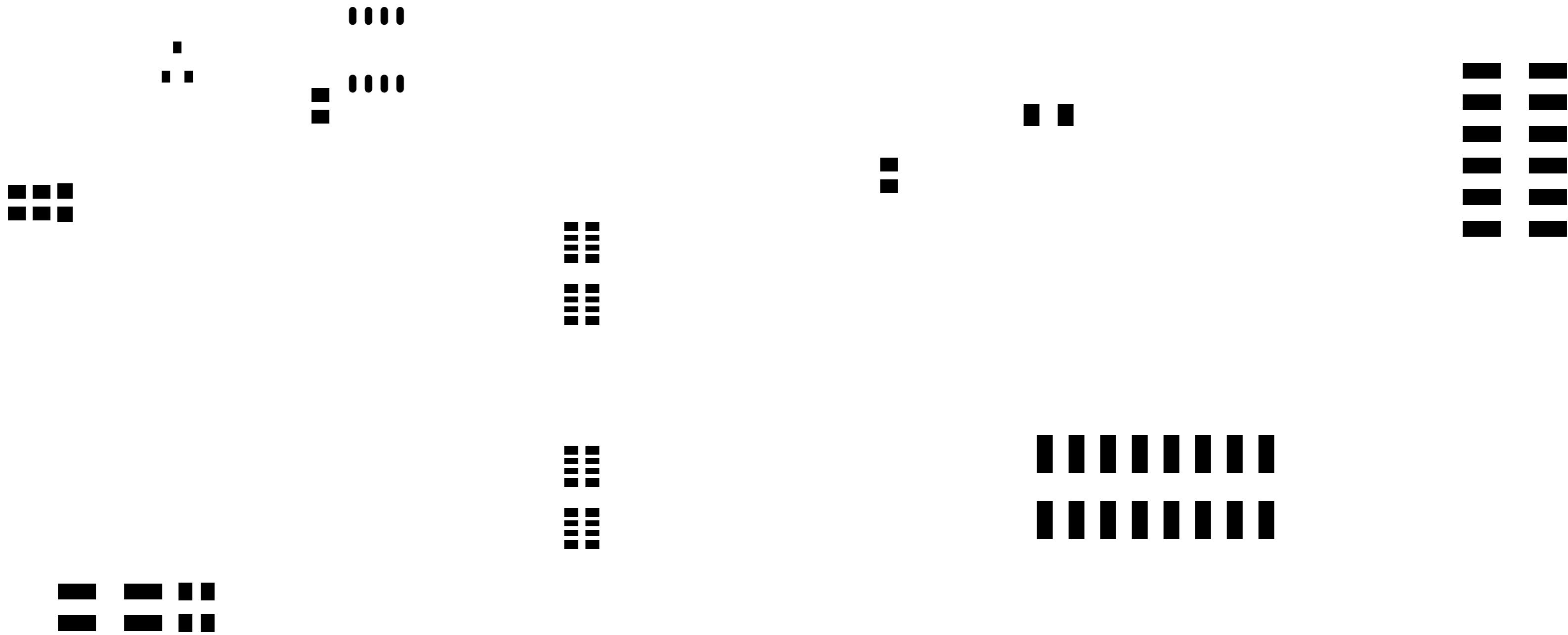
Diagram illustrating the sequence of events in the GED3 gene:

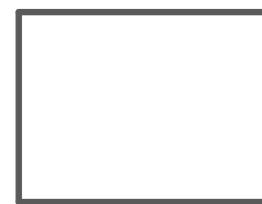
- The top row shows seven 'END' boxes, each connected by a dashed line to the right.
- The bottom row shows seven boxes labeled: GED3, RED3, EDI, EDO, BJ12, BJ14, and BJ13.
- A bracket on the left groups the first four boxes as MC (MC-GED3-RED3-EDI-EDO).
- A bracket on the right groups the last three boxes as CB (BJ12-BJ14-BJ13).

USE M3X.0 SCREWS

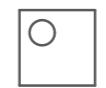
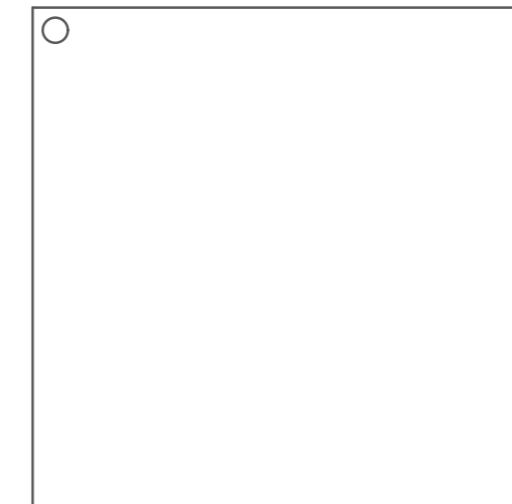
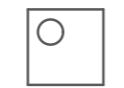
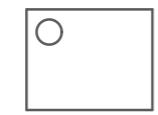


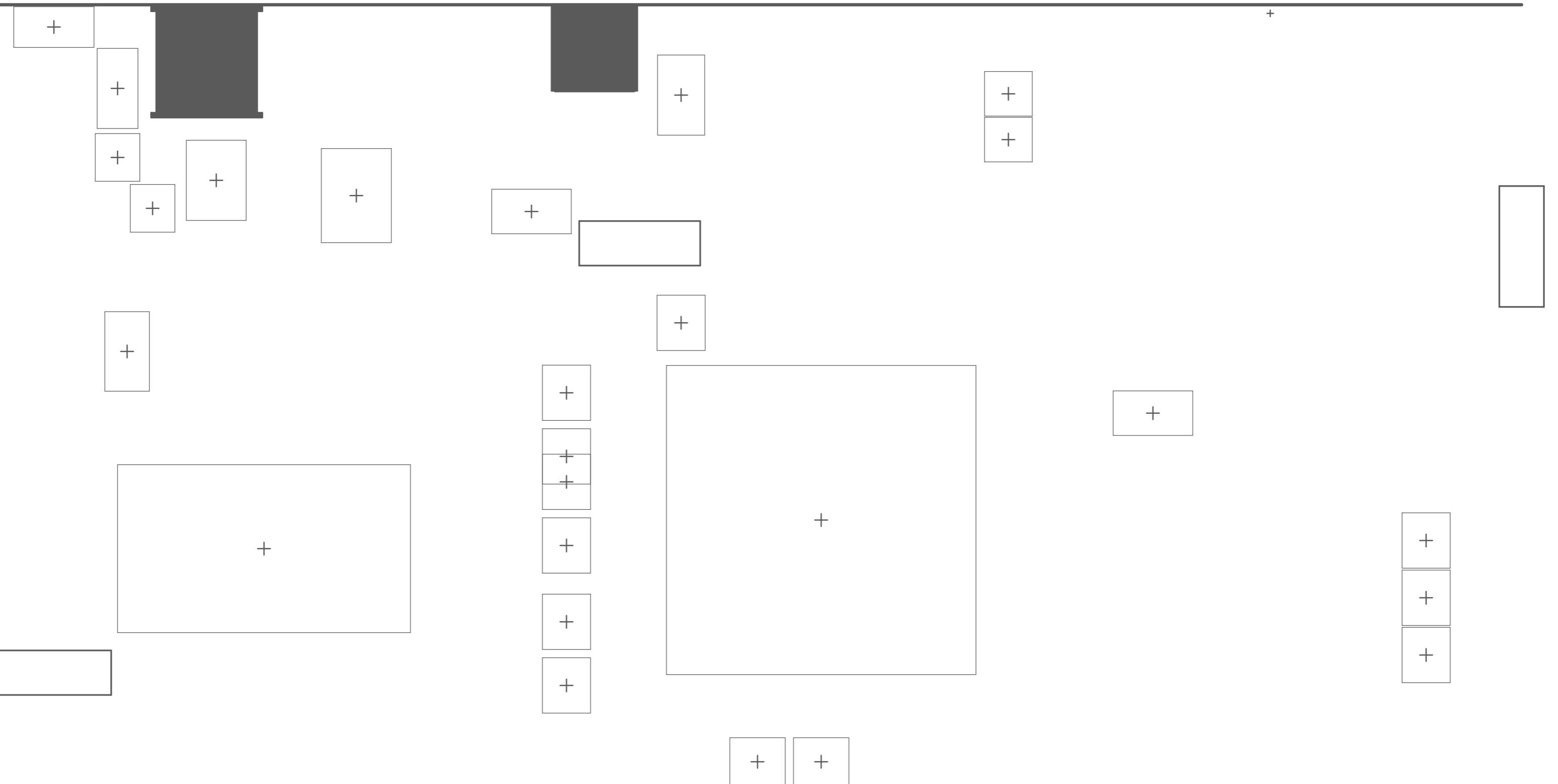




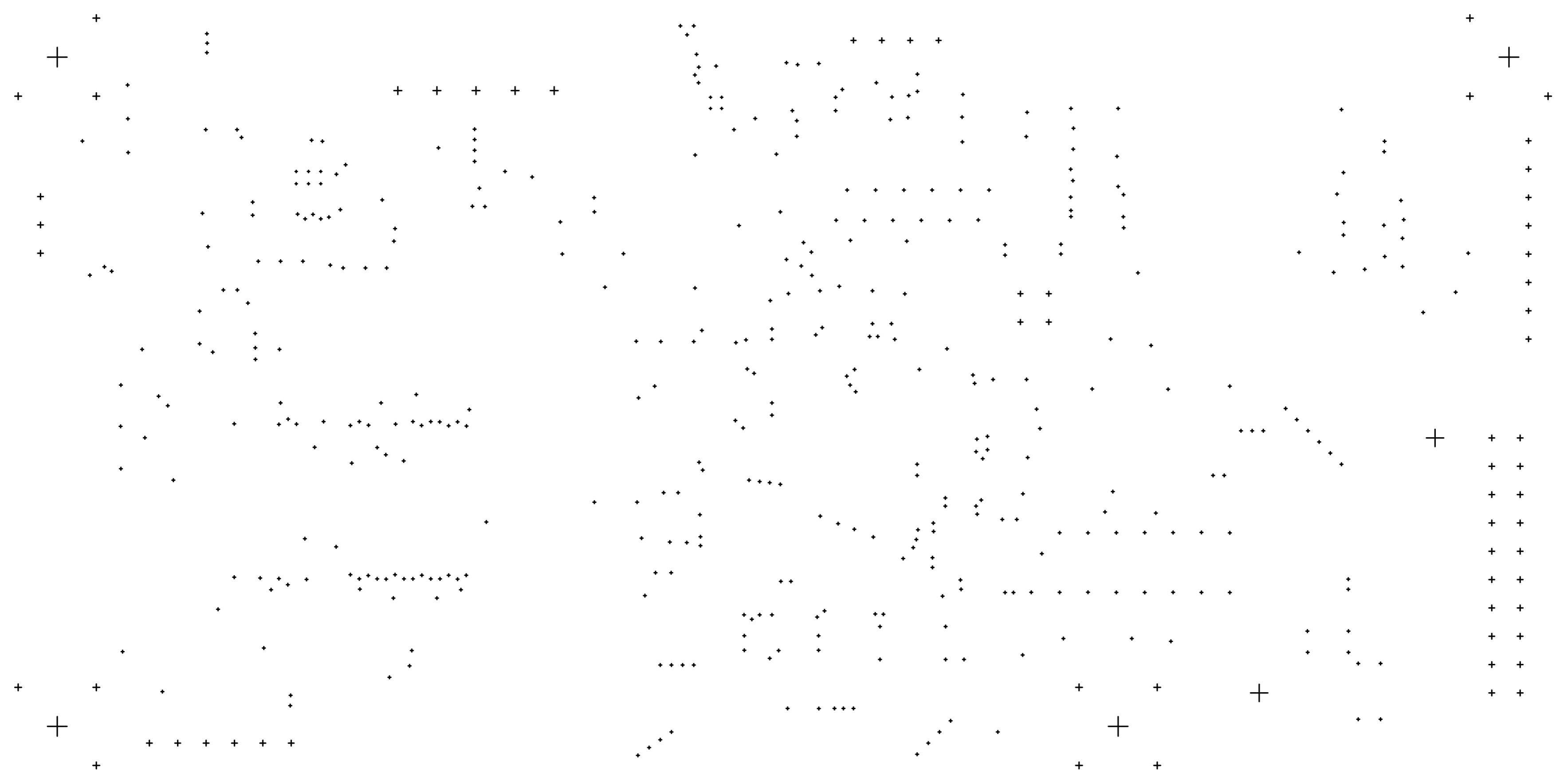


ANTENNA AREA  
CUTOUT POLYGON













**SOLENS**  
by Fluffy Logic

